

Ultra High Temperature Release Film



For Lamination of Rigid Multilayer and Flexible Circuits

PACOLON[®] is a line of ultra high performance Release Films with grades that withstand operating temperatures up to 500°F / 260°C. PACOLON films are engineered to provide excellent, contamination-free release during the process of laminating Rigid Polyimide PCBs, all Flexible Circuit Boards, Teflon and other demanding applications. These films provide a super smooth surface for adhesive and resin flow control [Flex Circuits], with low deformation under pressure [i.e., controlled, repeatable shrinkage].

PACOLON[®] ***RELEASE FILM FEATURES***

- Easy release at temperatures up to 500°F / 260°C
- Excellent flexibility
- Low X-Y axis shrinkage
- Ultra smooth surface finish, with superior conformal properties
- Inert and homogenous
- No separator plate residue, prepreg or vacuum system contamination
- Available in a range of custom thicknesses and widths

HIGH TEMPERATURE APPLICATIONS

- High Temperature Rigid Multilayer: To contain resin squeeze-out, protect copper from damaged plates, minimize X-Y axis stress from Aluminum plates, reduce plate cleaning, increase plate life. To prevent press pads from sticking to plates or bonding to tooling pins.
- High Temperature Flex and Rigid Flex: To contain adhesive bleed, completely conform to part topography, guarantee total separation of conformal hydraulics and driver pads from PCB surfaces.
- Microwave Circuit Materials / Teflon Boards

